EMC SOCIETY German Chapter

IEEE

EMC Professional Talk

Dr.-Ing.
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Electronic packaging for high-end Server,
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Böblingen, Germany

High-end Server Packaging: Trends and Challenges in Next Generations

The presentation provides an overview of current high end server packaging development challenges and solutions with the emphasis on electrical design, signal integrity, power delivery and power integrity. Followed by a discussion on where the industry is going with packaging technology and IO data rate and some of the challenges that entails for the electrical design and integration.

18.10.2022, 17:00 Uhr

Zoom:	https://ovgu.zoom.us/j/65212681357?pwd=T085Q3k5MUtUL01yaDhXNXkybkIzUT09
Meeting-ID:	**652 1268 1357**
Kenncode:	**751648**

About the speaker:

Xiaomin Duan received the B.S. degree in electrical engineering from Zhejiang University, China, in 2002, and the M.S. degree in microelectronics & microsystems and the Ph.D degree in electrical engineering, both from the Technical University Hamburg-Harburg, Germany, in 2007 and 2012, respectively. From July 2013 to December 2015, he was a post-doctoral researcher with Fraunhofer Institute für Zuverlässigkeit und Mikrointegration (IZM) in Berlin. Since 2016, He has been with IBM Deutschland Research & Development in Böblingen, responsible for electronic packaging development of high-end IBM Z and power series servers. His field of interests includes packaging technology, signal and power integrity, as well as electronic design methodologies.

Organisation:

Dr.-Ing. Miroslav Kotzev, Ericsson Antenna Technology Germany
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